

## 20V N-Channel Enhancement Mode MOSFET

**VDS= 20V**

RDS(ON), Vgs@ 4.5V, Ids@ 4.5A <25mΩ

RDS(ON), Vgs@ 2.5V, Ids@ 3.1A <45mΩ

### Features

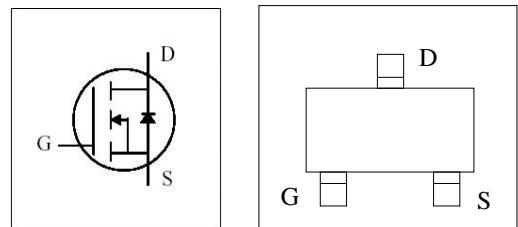
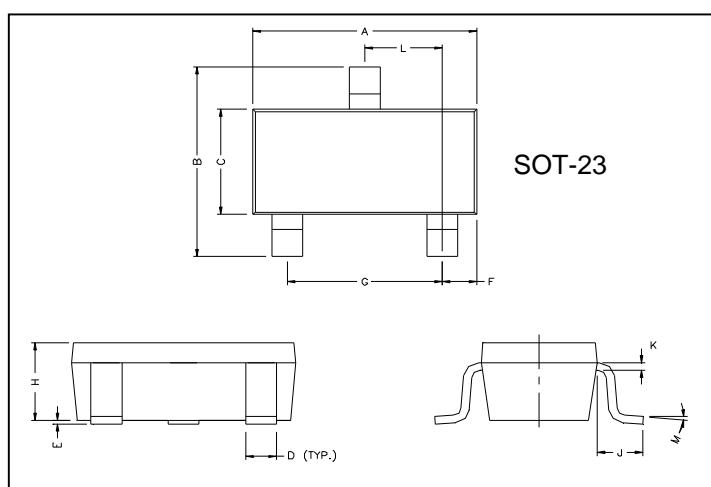
Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

High Power and Current handling capability

Ideal for Li ion battery pack applications

### Package Dimensions



REF.	Millimeter		REF.	Millimete	
	Min.	Max.		Min.	Max.
A	2.80	3.00	G	1.80	2.00
B	2.30	2.50	H	0.90	1.1
C	1.20	1.40	K	0.10	0.20
D	0.30	0.50	J	0.35	0.70
E	0	0.10	L	0.92	0.98
F	0.45	0.55	M	0°	10°

### Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	20	V
Gate-Source Voltage	V <sub>GS</sub>	± 10	
Continuous Drain Current	I <sub>D</sub>	4.6	A
Pulsed Drain Current <sup>1)</sup>	I <sub>DM</sub>	8	
Maximum Power Dissipation	TA = 25°C	P <sub>D</sub>	1.25
	TA = 75°C		0.8
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted) <sup>2)</sup>	R <sub>θJA</sub>	78	°C/W

#### Notes

1) Pulse width limited by maximum junction temperature.

2) Surface Mounted on FR4 Board, t ≤ 5 sec.

**ELECTRICAL CHARACTERISTICS (TA = 25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static<sup>3)</sup></b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 2.5V, I_D = 3.1A$		22.0	35.0	$m\Omega$
Drain-Source On-State Resistance	$R_{DS(on)}$			20.0	25.0	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.6	0.76		V
Zero Gate Voltage Drain Current 0	$I_{DSS}$	$V_{DS} = 20V, V_{GS} = 0V$			1	$\mu A$
Gate Body Leakage	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0V$			$\pm 100$	nA
Forward Transconductance	$g_f$	$V_{DS} = 5V, I_D = 4.2A$		5	—	S
<b>Dynamic<sup>4)</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = 10V, I_D = 3.6A$ $V_{GS} = 4.5V$		5.4	10	nC
Gate-Source Charge	$Q_{gs}$			0.65		
Gate-Drain Charge	$Q_{gd}$			1.5		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 10V, R_G = 6\Omega$ $I_D = 1A, V_{GS} = 4.5V$ $RL = 5.5\Omega$		12	25	ns
Turn-On Rise Time	$t_r$			36	60	
Turn-Off Delay Time	$t_{d(off)}$			34	60	
Turn-Off Fall Time	$t_f$			10	25	
Input Capacitance	$C_{iss}$	$V_{DS} = 10V, V_{GS} = 0V$ $f = 1.0 \text{ MHz}$		340		pF
Output Capacitance	$C_{oss}$			115		
Reverse Transfer Capacitance	$C_{rss}$			33		
<b>Source-Drain Diode</b>						
Max. Diode Forward Current	$I_s$				1.6	A
Diode Forward Voltage	$V_{SD}$	$I_s = 1.0A, V_{GS} = 0V$			1.0	V

**Notes**

3) Short duration test pulse used to minimize self-heating effect.

4) Pulse test pulse width <= 300us, duty cycle <= 2%.

